North America Advanced IC Substrates Market 2022-2031 by Packaging Type (FC BGA, FC CSP, Others), Material Type (Rigid, Flex, Ceramic), Manufacturing Method (SP, AP, MSAP), Bonding Technology (Wire Bonding, FC Bonding, TAB), Application (Mobile and Consumer Electronics, Automotive and Transportation, IT and Telecom, Others), and Country: Trend Forecast and Growth Opportunity

https://marketpublishers.com/r/N3455F398EBEEN.html
Date: April 2023
Pages: 125
Price: US$ 2,210.00 (Single User License)
ID: N3455F398EBEEN

Abstracts

North America advanced IC substrates market is projected to grow by 6.8% annually in the forecast period and reach $1,919.2 million by 2031, driven by the rising adoption of advanced substrates in manufacturing of electronics, the increasing prevalence and functionality of consumer electronic products sch as smart devices and smart wearables, and the increasing penetration of advanced technologies such as 5G and IoT connected devices.

Highlighted with 51 tables and 46 figures, this 125-page report “North America Advanced IC Substrates Market 2022-2031 by Packaging Type (FC BGA, FC CSP, Others), Material Type (Rigid, Flex, Ceramic), Manufacturing Method (SP, AP, MSAP), Bonding Technology (Wire Bonding, FC Bonding, TAB), Application (Mobile and Consumer Electronics, Automotive and Transportation, IT and Telecom, Others), and Country: Trend Forecast and Growth Opportunity” is based on a comprehensive research of the entire North America advanced IC substrates market and all its sub-segments through extensively detailed classifications. Profound analysis and assessment are generated from premium primary and secondary information sources

with inputs derived from industry professionals across the value chain. The report is based on studies on 2021-2022 and provides forecast from 2023 till 2031 with 2022 as the base year. (Please note: The report will be updated before delivery so that the latest historical year is the base year and the forecast covers at least 5 years over the base year.)

In-depth qualitative analyses include identification and investigation of the following aspects:

Market Structure

Growth Drivers

Restraints and Challenges

Emerging Product Trends & Market Opportunities

Porter's Fiver Forces

The trend and outlook of North America market is forecast in optimistic, balanced, and conservative view by taking into account of COVID-19 and Russia-Ukraine conflict. The balanced (most likely) projection is used to quantify North America advanced IC substrates market in every aspect of the classification from perspectives of Packaging Type, Material Type, Manufacturing Method, Bonding Technology, Application, and Country.

Based on Packaging Type, the North America market is segmented into the following sub-markets with annual revenue ($ mn) for 2022-2031 included in each section.

FC BGA

FC CSP

Other Packaging Types

Based on Material Type, the North America market is segmented into the following sub-markets with annual revenue ($ mn) for 2022-2031 included in each section.

+44 20 8123 2220
info@marketpublishers.com

Rigid Integrated Circuit Substrate

Flex Integrated Circuit Substrate

Ceramic Integrated Circuit Substrate

By Manufacturing Method, the North America market is segmented into the following sub-markets with annual revenue ($ mn) for 2022-2031 included in each section.

Subtraction Process (SP)

Addition Process (AP)

Modified Semi-additive Process (MSAP)

By Bonding Technology, the North America market is segmented into the following sub-markets with annual revenue ($ mn) for 2022-2031 included in each section.

Wire Bonding

FC Bonding

Tape Automated Bonding (TAB)

By Application, the North America market is segmented into the following sub-markets with annual revenue ($ mn) for 2022-2031 included in each section.

Mobile and Consumer Electronics

Automotive and Transportation

IT and Telecom

Other Applications

Geographically, the following national/local markets are fully investigated:

U.S.

Canada

Mexico

For each key country, detailed analysis and data for annual revenue ($ mn) are available for 2022-2031. The breakdown of national markets by Packaging Type, Material Type and Application over the forecast years is also included.

The report also covers the current competitive scenario and the predicted trend; and profiles key vendors including market leaders and important emerging players.

Selected Key Players:

ASE Group

AT&S Austria Technologie & Systemtechnik AG

Fujitsu Ltd.

IBIDEN Co., Ltd.

Kinsus Interconnect Technology Corp.

Korea Circuit Co., Ltd.

KYOCERA Corporation

LG Innotek Co., Ltd.

Nan Ya PCB Co., Ltd. (Nan Ya Plastics Corporation)

Shenzhen Fastprint Circuit Tech

Shinko Electric Industries Co., Ltd.

+44 20 8123 2220
info@marketpublishers.com

Siliconware Precision Industries Co., Ltd.

STATS ChipPAC Pte. Ltd. (JCET GROUP CO. LTD)

TTM Technologies Inc.

Unimicron Corporation

Zhen Ding Technology Holding Ltd.

Zhuhai ACCESS Semiconductor

(Please note: The report will be updated before delivery so that the latest historical year is the base year and the forecast covers at least 5 years over the base year.)

Contents

1 INTRODUCTION

1.1 Industry Definition and Research Scope
1.1.1 Industry Definition
1.1.2 Research Scope
1.2 Research Methodology
1.2.1 Overview of Market Research Methodology
1.2.2 Market Assumption
1.2.3 Secondary Data
1.2.4 Primary Data
1.2.5 Data Filtration and Model Design
1.2.6 Market Size/Share Estimation
1.2.7 Research Limitations
1.3 Executive Summary

2 MARKET OVERVIEW AND DYNAMICS

2.1 Market Size and Forecast
2.1.1 Impact of COVID-19 on World Economy
2.1.2 Impact of COVID-19 on the Market
2.1.3 Impact of Russia-Ukraine Conflict: War Slows Economic Recovery
2.2 Major Growth Drivers
2.3 Market Restraints and Challenges
2.4 Emerging Opportunities and Market Trends
2.5 Porter’s Fiver Forces Analysis

3 SEGMENTATION OF NORTH AMERICA MARKET BY PACKAGING TYPE

3.1 Market Overview by Packaging Type
3.2 FC BGA
3.3 FC CSP
3.4 Other Packaging Types

4 SEGMENTATION OF NORTH AMERICA MARKET BY MATERIAL TYPE

4.1 Market Overview by Material Type
4.2 Rigid Integrated Circuit Substrate

4.3 Flex Integrated Circuit Substrate
4.4 Ceramic Integrated Circuit Substrate

5 SEGMENTATION OF NORTH AMERICA MARKET BY MANUFACTURING METHOD

5.1 Market Overview by Manufacturing Method
5.2 Subtraction Process (SP)
5.3 Addition Process (AP)
5.4 Modified Semi-additive Process (MSAP)

6 SEGMENTATION OF NORTH AMERICA MARKET BY BONDING TECHNOLOGY

6.1 Market Overview by Bonding Technology
6.2 Wire Bonding
6.3 FC Bonding
6.4 Tape Automated Bonding (TAB)

7 SEGMENTATION OF NORTH AMERICA MARKET BY APPLICATION

7.1 Market Overview by Application
7.2 Mobile and Consumer Electronics
7.3 Automotive and Transportation
7.4 IT and Telecom
7.5 Other Applications

8 NORTH AMERICA MARKET 2021-2031 BY COUNTRY

8.1 Overview of North America Market
8.2 U.S.
8.3 Canada
8.4 Mexico

9 COMPETITIVE LANDSCAPE

9.1 Overview of Key Vendors
9.2 New Product Launch, Partnership, Investment, and M&A
9.3 Company Profiles
ASE Group

+44 20 8123 2220
info@marketpublishers.com

AT&S Austria Technologie & Systemtechnik AG
Fujitsu Ltd.
IBIDEN Co., Ltd.
Kinsus Interconnect Technology Corp.
Korea Circuit Co., Ltd.
KYOCERA Corporation
LG Innotek Co., Ltd.
Nan Ya PCB Co., Ltd. (Nan Ya Plastics Corporation)
Shenzhen Fastprint Circuit Tech
Shinko Electric Industries Co., Ltd.
Siliconware Precision Industries Co., Ltd.
STATS ChipPAC Pte. Ltd. (JCET GROUP CO. LTD)
TTM Technologies Inc.
Unimicron Corporation
Zhen Ding Technology Holding Ltd.
Zhuhai ACCESS Semiconductor
RELATED REPORTS

+44 20 8123 2220
info@marketpublishers.com

List Of Tables

LIST OF TABLES:

Table 1. Snapshot of North America Advanced IC Substrates Market in Balanced Perspective, 2021-2031
Table 2. World Economic Outlook, 2021-2031
Table 3. World Economic Outlook, 2021-2023
Table 4. Scenarios for Economic Impact of Ukraine Crisis
Table 5. World Semiconductor Market, 2021-2031, $ bn
Table 6. Main Product Trends and Market Opportunities in North America Advanced IC Substrates Market
Table 7. North America Advanced IC Substrates Market by Packaging Type, 2021-2031, $ mn
Table 8. North America Advanced IC Substrates Market by Material Type, 2021-2031, $ mn
Table 9. North America Advanced IC Substrates Market by Manufacturing Method, 2021-2031, $ mn
Table 10. North America Advanced IC Substrates Market by Bonding Technology, 2021-2031, $ mn
Table 11. North America Advanced IC Substrates Market by Application, 2021-2031, $ mn
Table 12. North America Advanced IC Substrates Market by Country, 2021-2031, $ mn
Table 13. U.S. Advanced IC Substrates Market by Packaging Type, 2021-2031, $ mn
Table 14. U.S. Advanced IC Substrates Market by Material Type, 2021-2031, $ mn
Table 15. U.S. Advanced IC Substrates Market by Application, 2021-2031, $ mn
Table 16. Canada Advanced IC Substrates Market by Packaging Type, 2021-2031, $ mn
Table 17. Canada Advanced IC Substrates Market by Material Type, 2021-2031, $ mn
Table 18. Canada Advanced IC Substrates Market by Application, 2021-2031, $ mn
Table 19. Mexico Advanced IC Substrates Market by Packaging Type, 2021-2031, $ mn
Table 20. Mexico Advanced IC Substrates Market by Material Type, 2021-2031, $ mn
Table 21. Mexico Advanced IC Substrates Market by Application, 2021-2031, $ mn
Table 22. ASE Group: Company Snapshot
Table 23. ASE Group: Business Segmentation
Table 24. ASE Group: Product Portfolio
Table 25. AT&S Austria Technologie & Systemtechnik AG: Company Snapshot
Table 26. AT&S Austria Technologie & Systemtechnik AG: Breakdown of Revenue by Business Segment

Table 27. Fujitsu Limited: Company Snapshot
Table 28. Fujitsu Limited: Business Segmentation and Share
Table 29. Fujitsu Limited: Revenue Distribution by Region in 2021
Table 30. IBIDEN Co., Ltd.: Company Snapshot
Table 31. IBIDEN Co., Ltd.: Breakdown of Revenue by Business Segment
Table 32. Kinsus Interconnect Technology Corp..: Company Snapshot
Table 33. Kinsus Interconnect Technology Corp.: Breakdown of Revenue by Business Segment
Table 34. Korea Circuit Co., Ltd.: Company Snapshot
Table 35. KYOCERA Corporation: Company Snapshot
Table 36. KYOCERA Corporation: Breakdown of Revenue by Business Segment
Table 37. LG Innotek Co., Ltd.: Company Snapshot
Table 38. Nan Ya PCB Co., Ltd.: Company Snapshot
Table 39. Shenzhen Fastprint Circuit Tech: Company Snapshot
Table 40. Shinko Electric Industries Co., Ltd.: Company Snapshot
Table 41. Shinko Electric Industries Co., Ltd.: Breakdown of Revenue by Business Segment
Table 42. Siliconware Precision Industries Co., Ltd.: Company Snapshot
Table 43. Siliconware Precision Industries Co., Ltd.: Breakdown of Revenue by Business Segment
Table 44. STATS ChipPAC Pte. Ltd.: Company Snapshot
Table 45. STATS ChipPAC Pte. Ltd.: Breakdown of Revenue by Business Segment
Table 46. TTM Technologies Inc.: Company Snapshot
Table 47. TTM Technologies Inc.: Breakdown of Revenue by Business Segment
Table 48. Unimicron Corporation: Company Snapshot
Table 49. Unimicron Corporation: Breakdown of Revenue by Business Segment
Table 50. Zhen Ding Technology Holding Ltd.: Company Snapshot
Table 51. Zhuhai ACCESS Semiconductor: Company Snapshot

List Of Figures

LIST OF FIGURES:

Figure 1. Research Method Flow Chart
Figure 2. Bottom-up Approach and Top-down Approach for Market Estimation
Figure 3. North America Market Forecast in Optimistic, Conservative and Balanced Perspectives, 2022-2031
Figure 4. Industry Value Chain Analysis
Figure 5. North America Advanced IC Substrates Market, 2021-2031, $ mn
Figure 6. Impact of COVID-19 on Business
Figure 7. Primary Drivers and Impact Factors of North America Advanced IC Substrates Market
Figure 8. World 5G Devices Market by Value, 2019-2030, $ bn
Figure 9. World Autonomous Vehicle Market, 2019-2030, $ mn
Figure 10. Primary Restraints and Impact Factors of North America Advanced IC Substrates Market
Figure 11. Investment Opportunity Analysis
Figure 12. Porter's Fiver Forces Analysis of North America Advanced IC Substrates Market
Figure 13. Breakdown of North America Advanced IC Substrates Market by Packaging Type, 2021-2031, % of Revenue
Figure 14. North America Addressable Market Cap in 2023-2031 by Packaging Type, Value ($ mn) and Share (%)
Figure 15. North America Advanced IC Substrates Market by Packaging Type: FC BGA, 2021-2031, $ mn
Figure 16. North America Advanced IC Substrates Market by Packaging Type: FC CSP, 2021-2031, $ mn
Figure 17. North America Advanced IC Substrates Market by Packaging Type: Other Packaging Types, 2021-2031, $ mn
Figure 18. Breakdown of North America Advanced IC Substrates Market by Material Type, 2021-2031, % of Sales Revenue
Figure 19. North America Addressable Market Cap in 2023-2031 by Material Type, Value ($ mn) and Share (%)
Figure 20. North America Advanced IC Substrates Market by Material Type: Rigid Integrated Circuit Substrate, 2021-2031, $ mn
Figure 21. North America Advanced IC Substrates Market by Material Type: Flex Integrated Circuit Substrate, 2021-2031, $ mn
Figure 22. North America Advanced IC Substrates Market by Material Type: Ceramic

Integrated Circuit Substrate, 2021-2031, $ mn
Figure 23. Breakdown of North America Advanced IC Substrates Market by Manufacturing Method, 2021-2031, % of Sales Revenue
Figure 24. North America Addressable Market Cap in 2023-2031 by Manufacturing Method, Value ($ mn) and Share (%)
Figure 25. North America Advanced IC Substrates Market by Manufacturing Method: Subtraction Process (SP), 2021-2031, $ mn
Figure 26. North America Advanced IC Substrates Market by Manufacturing Method: Addition Process (AP), 2021-2031, $ mn
Figure 27. North America Advanced IC Substrates Market by Manufacturing Method: Modified Semi-additive Process (MSAP), 2021-2031, $ mn
Figure 28. Breakdown of North America Advanced IC Substrates Market by Bonding Technology, 2021-2031, % of Revenue
Figure 29. North America Addressable Market Cap in 2023-2031 by Bonding Technology, Value ($ mn) and Share (%)
Figure 30. North America Advanced IC Substrates Market by Bonding Technology: Wire Bonding, 2021-2031, $ mn
Figure 31. Picture of Wire Bonding Illustrated in a DIP Package
Figure 32. North America Advanced IC Substrates Market by Bonding Technology: FC Bonding, 2021-2031, $ mn
Figure 33. Picture of a Flipped Chip (IC) on a Passive Substrate
Figure 34. North America Advanced IC Substrates Market by Bonding Technology: Tape Automated Bonding (TAB), 2021-2031, $ mn
Figure 35. Breakdown of North America Advanced IC Substrates Market by Application, 2021-2031, % of Revenue
Figure 36. North America Addressable Market Cap in 2023-2031 by Application, Value ($ mn) and Share (%)
Figure 37. North America Advanced IC Substrates Market by Application: Mobile and Consumer Electronics, 2021-2031, $ mn
Figure 38. North America Advanced IC Substrates Market by Application: Automotive and Transportation, 2021-2031, $ mn
Figure 39. North America Advanced IC Substrates Market by Application: IT and Telecom, 2021-2031, $ mn
Figure 40. North America Advanced IC Substrates Market by Application: Other Applications, 2021-2031, $ mn
Figure 41. Breakdown of North America Advanced IC Substrates Market by Country, 2022 and 2031, % of Revenue
Figure 42. Contribution to North America 2023-2031 Cumulative Market by Country, Value ($ mn) and Share (%)

+44 20 8123 2220
info@marketpublishers.com

Figure 43. U.S. Advanced IC Substrates Market, 2021-2031, $ mn
Figure 44. Canada Advanced IC Substrates Market, 2021-2031, $ mn
Figure 45. Advanced IC Substrates Market in Mexico, 2021-2031, $ mn
Figure 46. Growth Stage of North America Advanced IC Substrates Industry over the Forecast Period

+44 20 8123 2220
info@marketpublishers.com

I would like to order

Product name: North America Advanced IC Substrates Market 2022-2031 by Packaging Type (FC BGA, FC CSP, Others), Material Type (Rigid, Flex, Ceramic), Manufacturing Method (SP, AP, MSAP), Bonding Technology (Wire Bonding, FC Bonding, TAB), Application (Mobile and Consumer Electronics, Automotive and Transportation, IT and Telecom, Others), and Country: Trend Forecast and Growth Opportunity

Product link: https://marketpublishers.com/r/N3455F398EBEEN.html

Price: US$ 2,210.00 (Single User License / Electronic Delivery)

If you want to order Corporate License or Hard Copy, please, contact our Customer Service:

info@marketpublishers.com

Payment

To pay by Credit Card (Visa, MasterCard, American Express, PayPal), please, click button on product page https://marketpublishers.com/r/N3455F398EBEEN.html

To pay by Wire Transfer, please, fill in your contact details in the form below:

First name:

Last name:

Email:

Company:

Address:

City:

Zip code:

Country:

Tel:

Fax:

Your message:

**All fields are required

Custumer signature ______________________________________

Please, note that by ordering from marketpublishers.com you are agreeing to our Terms & Conditions at https://marketpublishers.com/docs/terms.html

+44 20 8123 2220
info@marketpublishers.com

To place an order via fax simply print this form, fill in the information below and fax the completed form to +44 20 7900 3970